## 503141644 01/20/2015

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3188256

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
CHIN-HAN PAN	01/08/2015
YAO-FENG HUANG	01/08/2015

#### **RECEIVING PARTY DATA**

Name:	NUVOTON TECHNOLOGY CORPORATION	
Street Address:	NO.4,CREATION RD. III HSINCHU SCIENCE PARK,	
City:	HSINCHU	
State/Country:	TAIWAN	

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14596237

### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	49384-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	01/20/2015

**Total Attachments: 2** 

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PATENT 503141644 REEL: 034748 FRAME: 0056

102-018-NTC 49384-US-PA

#### ASSIGNMENT

#### WHEREAS.

1. Chin-Han Pan

2. Yao-Feng Huang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME

[ ] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Nuvoton Technology Corporation

of No.4,Creation Rd. III Hsinchu Science Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

# **ASSIGNMENT CONTINUED**

IN TESTIMONY	WHEREOF, Assignor	has/have signed	his/her/their n	ame(s) on the	date(s)
indicated.					

Date:	Jan.08,2015	
	Date: _	Date: Jan.08,2015

Sole or First Joint Inventor: Chin-Han Pan

Second Joint Inventor (if any): Yao-Feng Huang

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